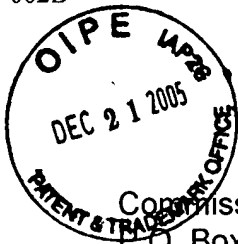


JFW



December 19, 2005

TO: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Attn: Art Unit 2813 - Examiner Mitchell, James M

FROM: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 10/826,752
File Date: 04/16/2004
Inventor: Romeo Emmanuel P. Alvarez
Examiner: Mitchell, James M.
Art Unit: 2813
Title: Method for Forming a Wafer Level Chip Scale Package and
Package Formed Thereby


RESPONSE TO RESTRICTION REQUIREMENT

Dear Sir:

This is in response to the Restriction Requirement in the Office Action dated Oct. 17, 2005. In that office action, restriction was required to one of the following Inventions under

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents P.O. Box 1450, Alexandria, VA 22313-1450 on Dec. 19, 2005.

Signature 
Stephen B. Ackerman, Reg. No. 37,761

Date: Dec. 19, 2005